



## Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D *: Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2022-06-23
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Representative Title	ADG Material Declaration champion
Authorized Representative *	giovanni giacopello	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPM802	B0E5*UR6JCBP	A	P1C7	2022-06-23
	Amount	UoM	Unit type	ST ECOPACK Grade
	69	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00877537	

Package Designator	Package Size	Nbr of instances	Shape	
Not Applicable	5x5x0.9	36	0	
Comment	VFQFN 5X5X0.9 32+4L WETT. FLANKS			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description

QueryList : California Prop65 list, dated 17th Dec 2021			
Query	Response		
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	true		
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	false		
Substance	amount in product (mg)	Application	ppm in product

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014				
Query	Response			
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
Hazardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
O	O	O	O	O

QueryList : REACH-17 Jan 2022				
Query	Response			
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	true			
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article / Homogeneous Material

QueryList : Responsible metals sourcing	
Query	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present in the component :	Cobalt, Tin, Tungsten,
This product is in the scope of the responsible metals sourcing, its compliance is covered by our company processes .	

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	
Query	Response
The Product does contain at least one of the substances listed in Chemical Control Act	false

China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	
Query	Response
The product contains adhesives identified under GB 33372	true
All the adhesive impacted complies with GB 33372	true

Stockholm Convention Persistent Organic Pollutants	
Query	Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	true

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	BOE5*UR6ICBP					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	6.963	mg	supplier	die	Silicon(Si)	7440-21-3		6.142	mg	882091	89016
				supplier	metallisation	Copper(Cu)	7440-50-8		0.560	mg	80425	8116
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.001	mg	144	14
				supplier	metallisation	Palladium(Pd)	7440-05-3		0.020	mg	2872	290
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	144	14
				supplier	metallisation	Tungsten(W)	7440-33-7		0.028	mg	3734	377
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.028	mg	4021	406
				supplier	passivation	Silicon oxide	7631-86-9		0.090	mg	12925	1304
				supplier	polymer coating	polyimide	proprietary		0.095	mg	13644	1377
				supplier	alloy	Copper(Cu)	7440-50-8		30.833	mg	974587	446855
Leadframe	M-004 Copper and its alloys	31.637	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.543	mg	17163	7870
				supplier	alloy	Iron phosphide	26508-33-8		0.126	mg	3983	1826
				supplier	alloy	Zinc(Zn)	7440-66-6		0.040	mg	1264	580
				supplier	metallization	Silver (Ag)	7440-22-4		0.095	mg	3003	1377
				supplier	glue	Silver(Ag)	7440-22-4		0.914	mg	844731	13246
Die attach	M-011 Other inorganic materials	1.082	mg	supplier	glue	Bismaleimide resin	proprietary		0.147	mg	135860	2130
				supplier	glue	Additives	proprietary		0.021	mg	19409	304
				supplier	wire	Copper(Cu)	7440-50-8		0.574	mg	1000000	8319
Bonding wires	M-004 Copper and its alloys	0.574	mg	supplier	wire	Copper(Cu)	7440-50-8		0.574	mg	1000000	8319
Bonding wires 2	M-004 Copper and its alloys	0.472	mg	supplier	wire	Copper(Cu)	7440-50-8		0.472	mg	1000000	6841
Encapsulation	M-011 Other inorganic materials	28.260	mg	supplier	mold compound	Silica vitreous	60676-86-0		24.869	mg	880007	360420
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		1.413	mg	50000	20478
				supplier	mold compound	Phenolic resin	205830-20-2		1.102	mg	38995	15971
				supplier	mold compound	Epoxy type resin	proprietary		0.565	mg	19993	8188
				supplier	mold compound	Carbon black	1333-86-4		0.057	mg	2017	826
				supplier	mold compound	other	proprietary		0.254	mg	8988	3681
Connections coating	Solder	0.012	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.012	mg	1000000	174